



Description

The 16N65 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

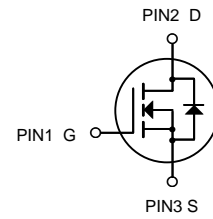


TO-263

General Features

$V_{DS} = 650V$ $I_D = 16A$

$R_{DS(ON)} < 0.55\Omega @ V_{GS}=10V$



N-Channel MOSFET

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

| Product ID | Pack | Marking | Qty(PCS) |
|------------|--------|-----------------|----------|
| 16N65 | TO-263 | 16N65 XXXX YYYY | 800 |

Absolute Maximum Ratings

| Symbol | Parameter | Limit | Units |
|-----------------|---|------------|---------------|
| V_{DS} | Drain-Source Voltage | 650 | V |
| V_{GS} | Gate-Source Voltage | ± 30 | V |
| I_D | Drain Current-Continuous | 16 | A |
| I_{DM} | Drain Current-Pulsed ^a | 64 | A |
| P_D | Maximum Power Dissipation @ $T_C = 25^\circ C$ - Derate above $25^\circ C$ | 180 | W |
| | | 1.1 | W/ $^\circ C$ |
| E_{AS} | Single Pulsed Avalanche Energy ^d | 1000 | mJ |
| I_{AS} | Single Pulsed Avalanche Current ^d | 64 | A |
| T_J, T_{stg} | Operating and Store Temperature Range | -55 to 175 | $^\circ C$ |
| $R_{\theta JC}$ | Thermal Resistance, Junction-to-Case | 0.69 | $^\circ C/W$ |
| $R_{\theta JA}$ | Thermal Resistance, Junction-to-Ambient | 62.5 | $^\circ C/W$ |



Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Min. | Typ. | Max. | Unit | Test Conditions |
|--------------|---|------|------|------|----------|---|
| BV_{DSS} | Drain-to-Source Breakdown Voltage | 650 | -- | -- | V | $V_{GS}=0V, I_D=250\mu A$ |
| I_{DSS} | Drain-to-Source Leakage Current | -- | -- | 1.0 | μA | $V_{DS}=650V, V_{GS}=0V$ |
| | | -- | -- | 100 | | $V_{DS}=520V, V_{GS}=0V, T_J=125^\circ C$ |
| I_{GSS} | Gate-to-Source Leakage Current | -- | -- | +100 | nA | $V_{GS}=+30V, V_{DS}=0V$ |
| | | -- | -- | -100 | | $V_{GS}=-30V, V_{DS}=0V$ |
| $R_{DS(ON)}$ | Static Drain-to-Source On-Resistance ^[4] | -- | 0.45 | 0.55 | Ω | $V_{GS}=10V, I_D=8A$ |
| $V_{GS(TH)}$ | Gate Threshold Voltage | 2.0 | -- | 4.0 | V | $V_{DS}=V_{GS}, I_D=250\mu A$ |
| g_{fs} | Forward Transconductance ^[4] | -- | 15 | -- | S | $V_{DS}=15V, I_D=8A$ |
| C_{iss} | Input Capacitance | -- | 2442 | -- | pF | $V_{GS}=0V, V_{DS}=25V, f=1.0MHz$ |
| C_{rss} | Reverse Transfer Capacitance | -- | 18.5 | -- | | |
| C_{oss} | Output Capacitance | -- | 218 | -- | | |
| Q_g | Total Gate Charge | -- | 54 | -- | nC | $V_{DD}=325V, I_D=16A, V_{GS}=0 \text{ to } 10V$ |
| Q_{gs} | Gate-to-Source Charge | -- | 12 | -- | | |
| Q_{gd} | Gate-to-Drain (Miller) Charge | -- | 21 | -- | | |
| $t_{d(ON)}$ | Turn-on Delay Time | -- | 15 | -- | nS | $V_{DD}=325V, I_D=16A, V_{GS}=10V, R_G=6.1\Omega$ |
| t_{rise} | Rise Time | -- | 52 | -- | | |
| $t_{d(OFF)}$ | Turn-Off Delay Time | -- | 59 | -- | | |
| t_{fall} | Fall Time | -- | 72 | -- | | |
| I_{SD} | Continuous Source Current ^[4] | -- | -- | 16 | A | Integral PN-diode in MOSFET |
| I_{SM} | Pulsed Source Current ^[4] | -- | -- | 64 | | |
| V_{SD} | Diode Forward Voltage | -- | -- | 1.5 | V | $I_S=16A, V_{GS}=0V$ |
| t_{rr} | Reverse recovery time | -- | 380 | -- | V | $V_{GS}=0V, I_F=16A, di_F/dt=100A/\mu s$ |
| Q_{rr} | Reverse recovery charge | -- | 2.6 | -- | μC | |

Note:

[1] $T_J=+25^\circ C$ to $+150^\circ C$

[2] Repetitive rating; pulse width limited by maximum junction temperature.

[3] $I_{SD}=16A, di/dt < 100 A/\mu s, V_{DD} < BV_{DSS}, T_J=+150^\circ C$.

[4] Pulse width $\leq 380\mu s$; duty cycle $\leq 2\%$.



Typical Characteristics

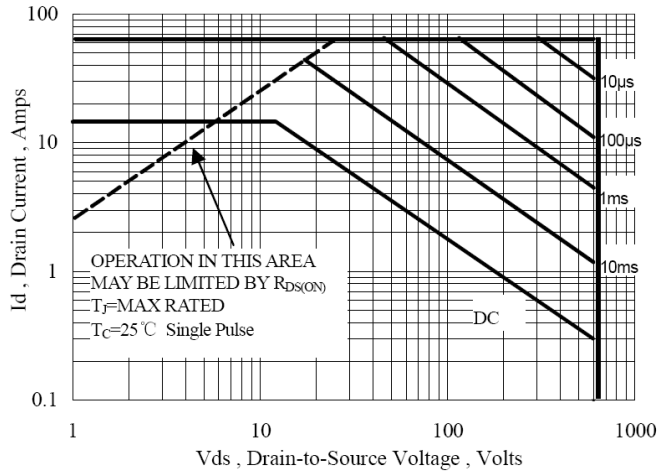


Figure 1 Maximum Forward Bias Safe Operating Area

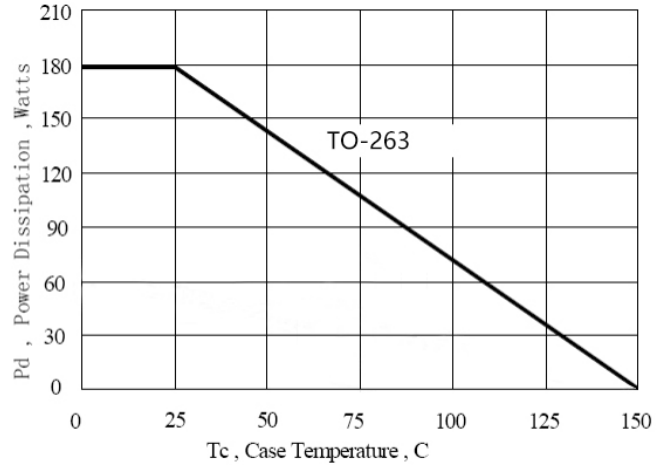


Figure 2 Maximum Power Dissipation vs Case Temperature

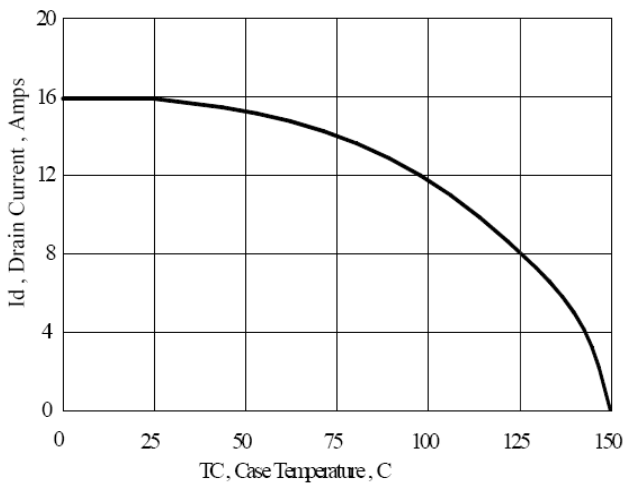


Figure 3 Maximum Continuous Drain Current vs Case Temperature

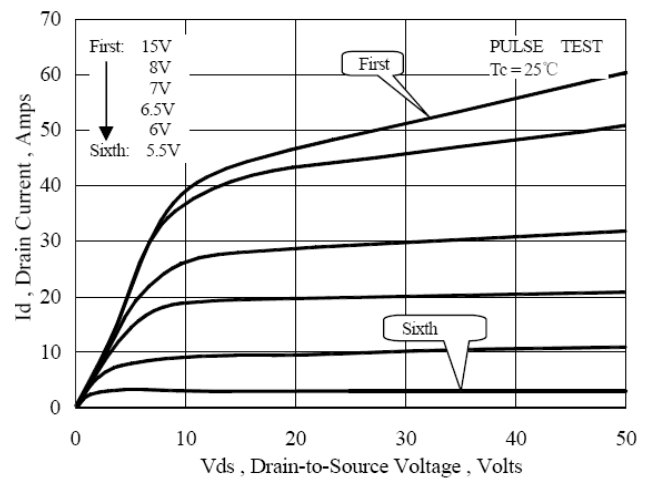


Figure 4 Typical Output Characteristics

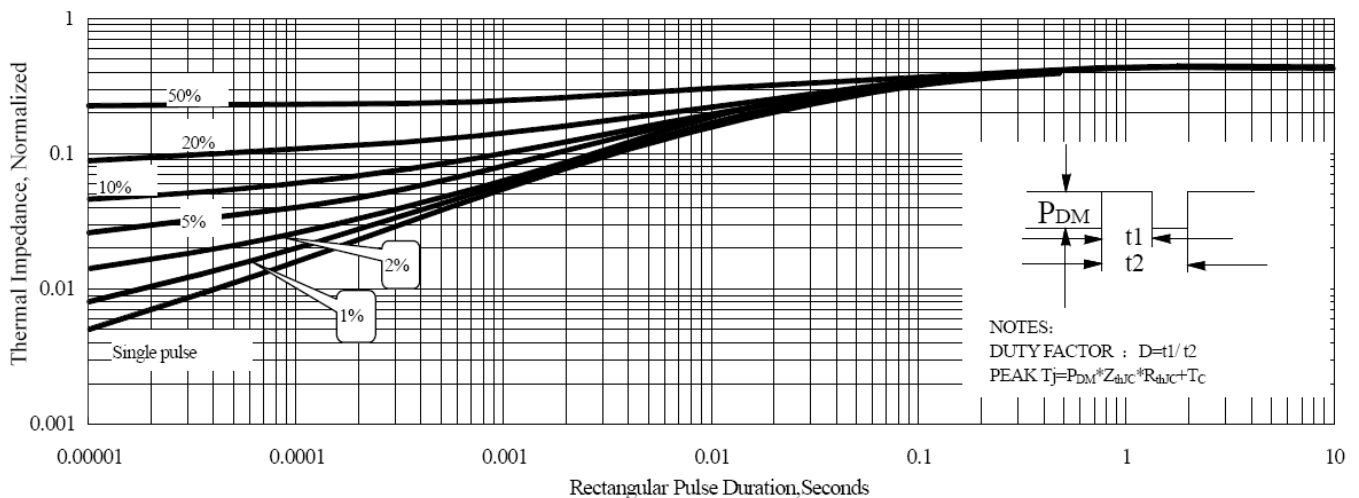


Figure 5 Maximum Effective Thermal Impedance, Junction to Case

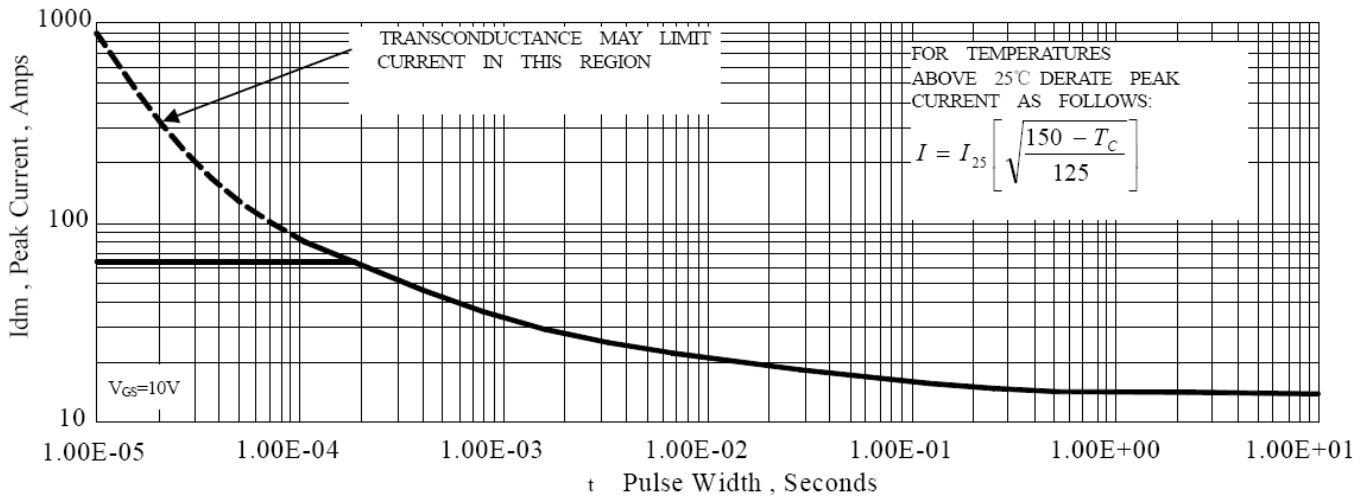


Figure 6 Maximum Peak Current Capability

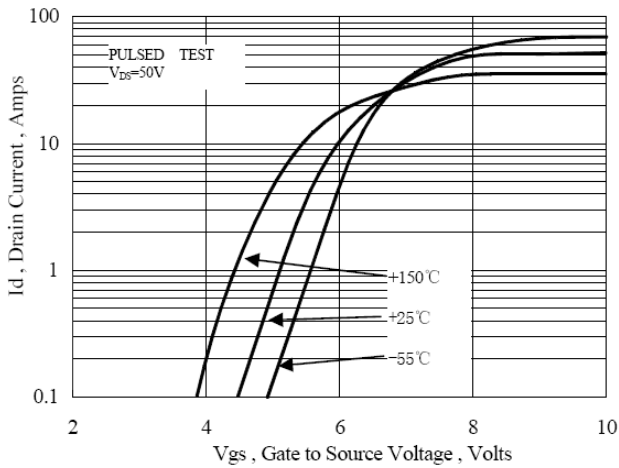


Figure 7 Typical Transfer Characteristics

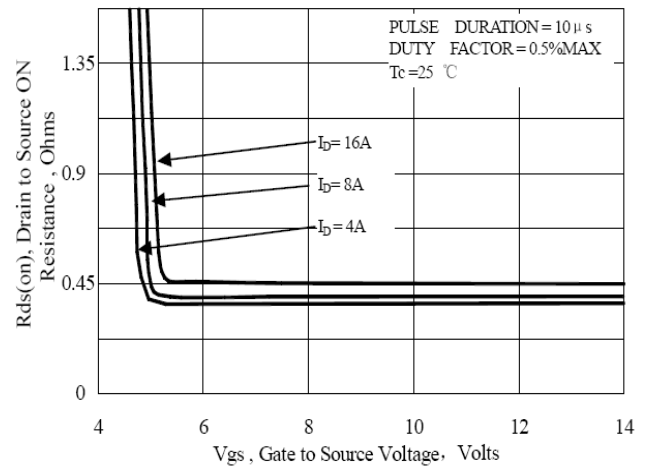


Figure 8 Typical Drain to Source ON Resistance vs Gate Voltage

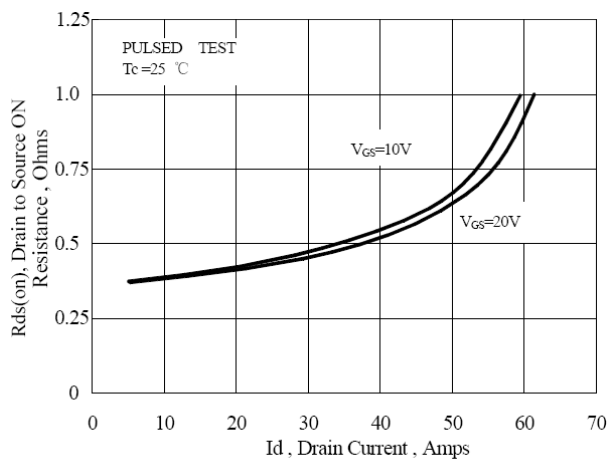


Figure 9 Typical Drain to Source ON Resistance vs Drain Current

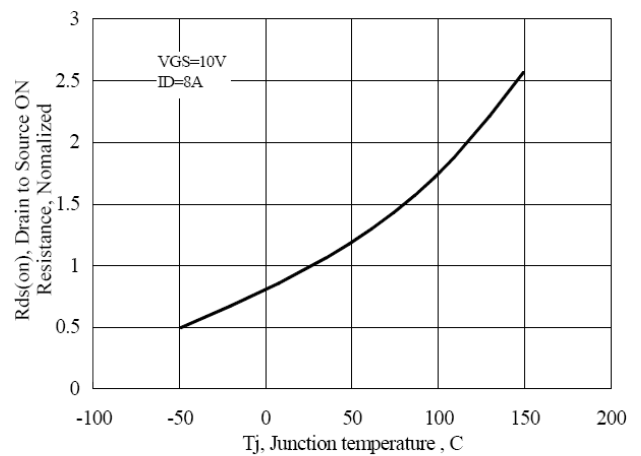


Figure 10 Typical Drain to Source ON Resistance vs Junction Temperature

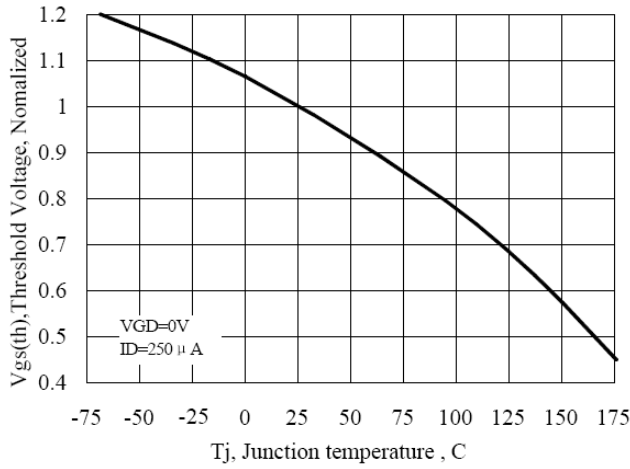


Figure 11 Typical Threshold Voltage vs Junction Temperature

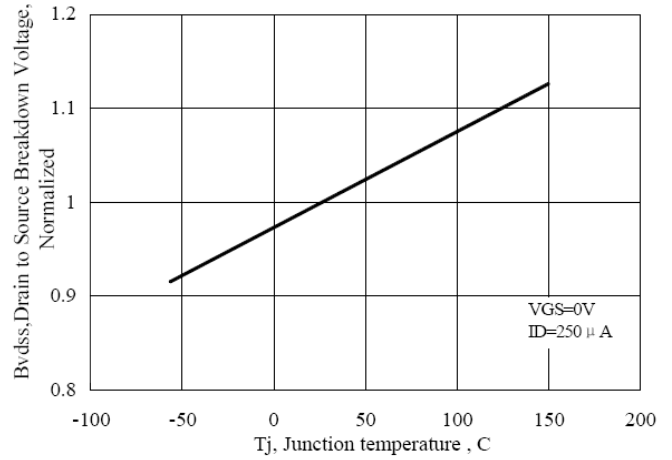


Figure 12 Typical Breakdown Voltage vs Junction Temperature

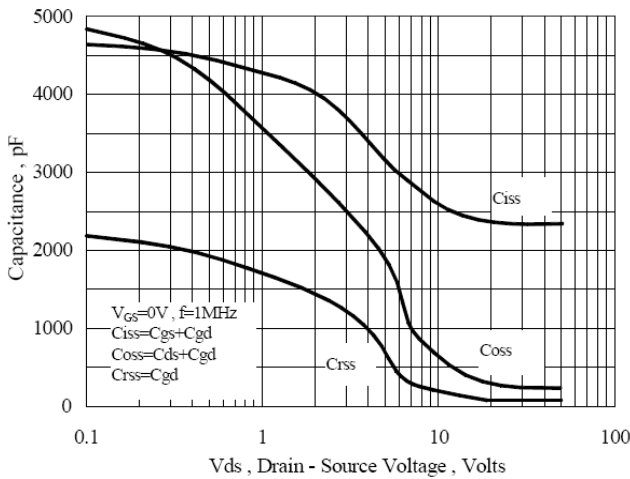


Figure 13 Typical Capacitance vs Drain to Source Voltage

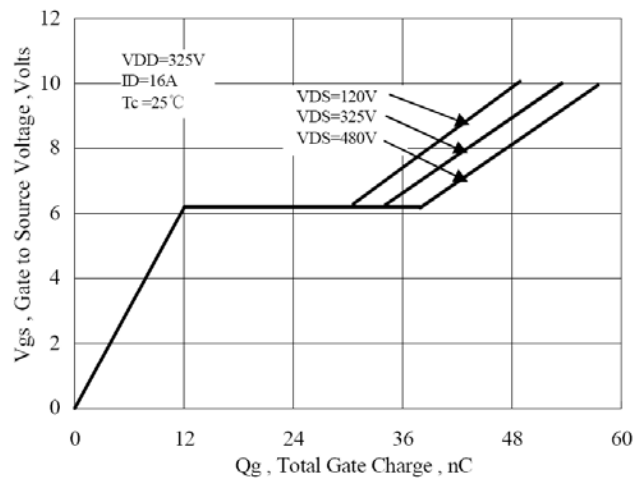


Figure 14 Typical Gate Charge vs Gate to Source Voltage

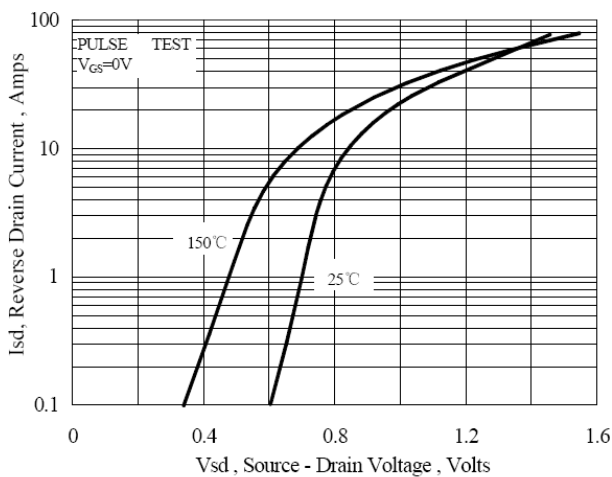


Figure 15 Typical Body Diode Transfer Characteristics

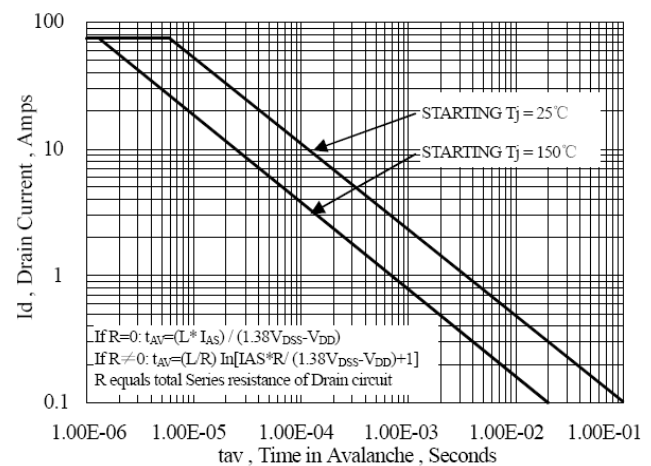


Figure 16 Unclamped Inductive Switching Capability



Test Circuits and Waveforms

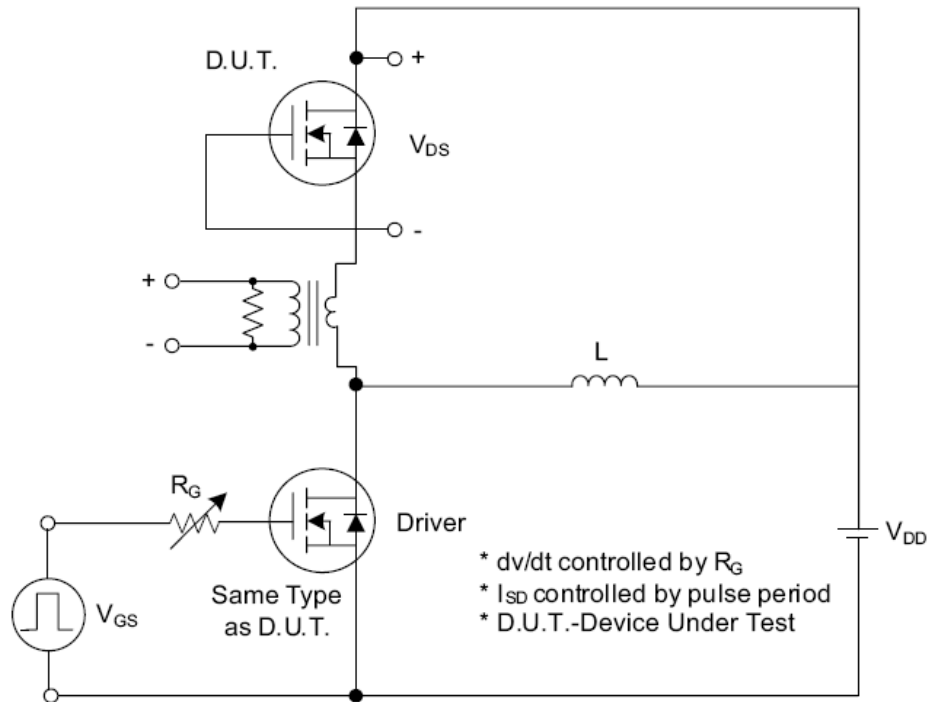


Fig. 1.1 Peak Diode Recovery dv/dt Test Circuit

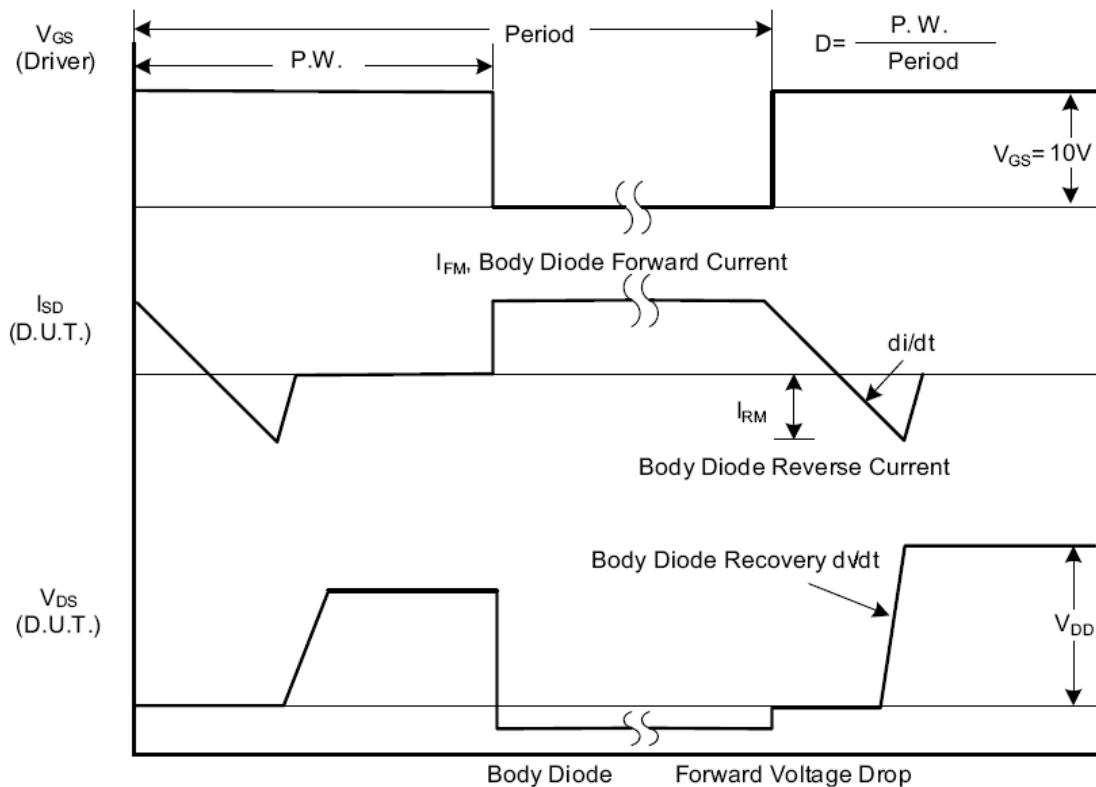


Fig. 1.2 Peak Diode Recovery dv/dt Waveforms



Test Circuits and Waveforms (Cont.)

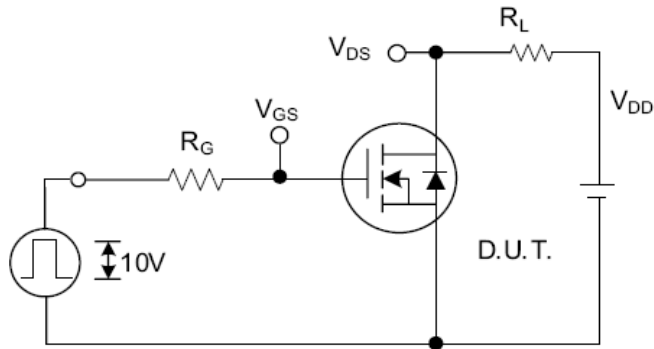


Fig. 2.1 Switching Test Circuit

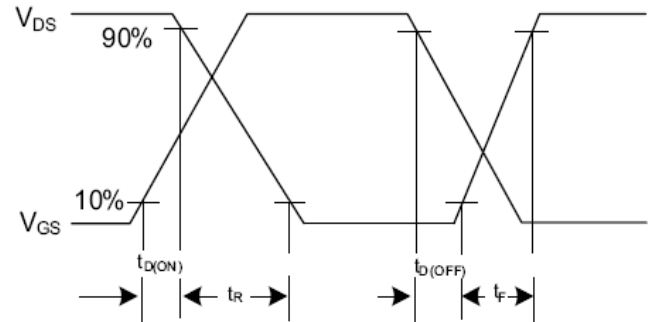


Fig. 2.2 Switching Waveforms

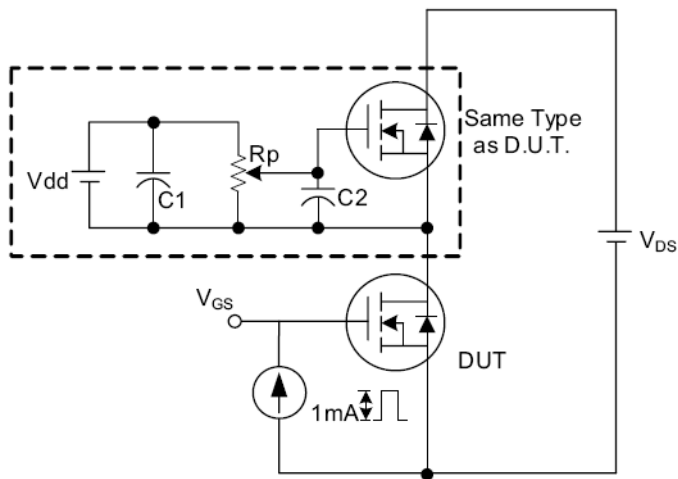


Fig. 3.1 Gate Charge Test Circuit

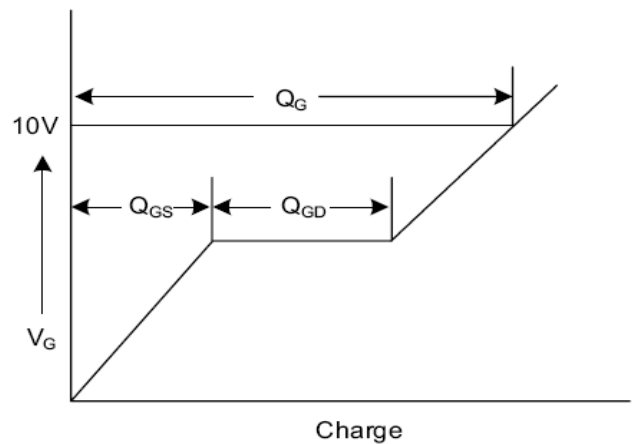


Fig. 3.2 Gate Charge Waveform

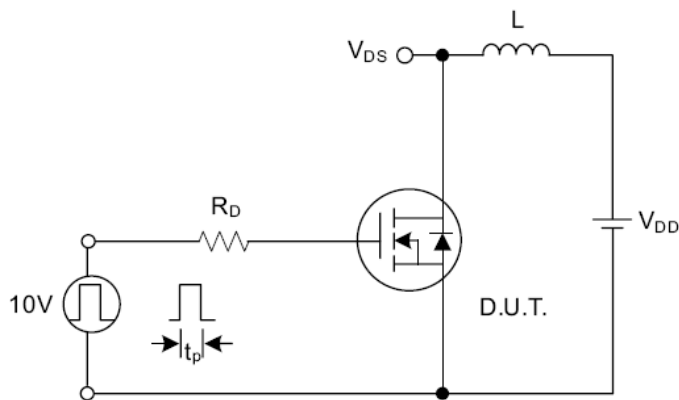


Fig. 4.1 Unclamped Inductive Switching Test Circuit

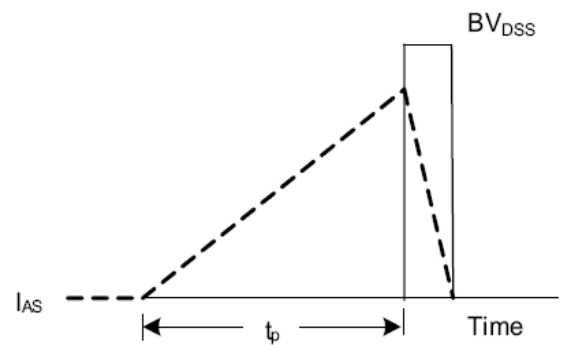
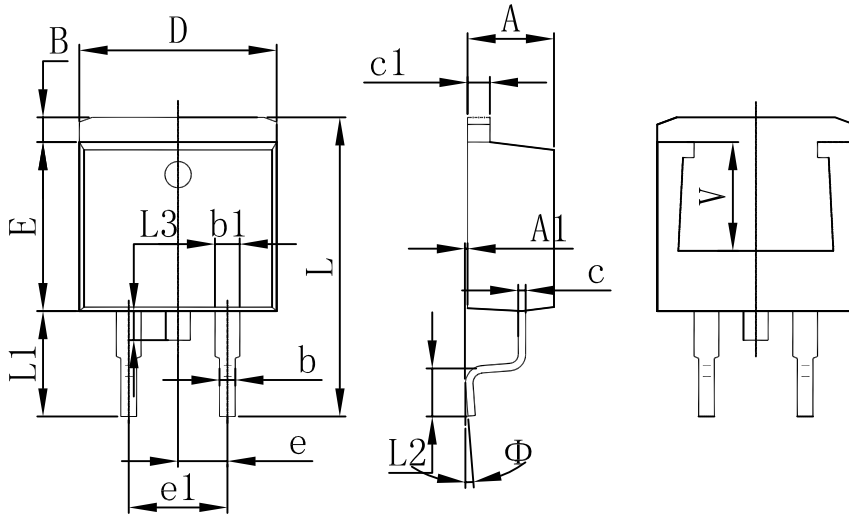


Fig. 4.2 Unclamped Inductive Switching Waveforms



TO-263 Package Outline Dimensions



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|--------|----------------------|-------|
| | Min. | Max. | Min. | Max. |
| A | 4.470 | 4.670 | 0.176 | 0.184 |
| A1 | 0.000 | 0.150 | 0.000 | 0.006 |
| B | 1.120 | 1.420 | 0.044 | 0.056 |
| b | 0.710 | 0.910 | 0.028 | 0.036 |
| b1 | 1.170 | 1.370 | 0.046 | 0.054 |
| c | 0.310 | 0.530 | 0.012 | 0.021 |
| c1 | 1.170 | 1.370 | 0.046 | 0.054 |
| D | 10.010 | 10.310 | 0.394 | 0.406 |
| E | 8.500 | 8.900 | 0.335 | 0.350 |
| e | 2.540 TYP. | | 0.100 TYP. | |
| e1 | 4.980 | 5.180 | 0.196 | 0.204 |
| L | 14.940 | 15.500 | 0.588 | 0.610 |
| L1 | 4.950 | 5.450 | 0.195 | 0.215 |
| L2 | 2.340 | 2.740 | 0.092 | 0.108 |
| L3 | 1.300 | 1.700 | 0.051 | 0.067 |
| Φ | 0° | 8° | 0° | 8° |
| V | 5.600 REF. | | 0.220REF. | |



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